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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16c73a-04-so">https://www.e-xfl.com/product-detail/microchip-technology/pic16c73a-04-so</a>


# PIC16C7X

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NOTES:

**FIGURE 4-4: PIC16C72 REGISTER FILE MAP**


File Address			File Address
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADDD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h	General Purpose Register	General Purpose Register	A0h
			BFh
			C0h
7Fh	Bank 0	Bank 1	FFh

 Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

**FIGURE 4-5: PIC16C73/73A/74/74A REGISTER FILE MAP**

File Address			File Address
00h	INDF <sup>(1)</sup>	INDF <sup>(1)</sup>	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	PORTC	TRISC	87h
08h	PORTD <sup>(2)</sup>	TRISD <sup>(2)</sup>	88h
09h	PORTE <sup>(2)</sup>	TRISE <sup>(2)</sup>	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh	PIR2	PIE2	8Dh
0Eh	TMR1L	PCON	8Eh
0Fh	TMR1H		8Fh
10h	T1CON		90h
11h	TMR2		91h
12h	T2CON	PR2	92h
13h	SSPBUF	SSPADD	93h
14h	SSPCON	SSPSTAT	94h
15h	CCPR1L		95h
16h	CCPR1H		96h
17h	CCP1CON		97h
18h	RCSTA	TXSTA	98h
19h	TXREG	SPBRG	99h
1Ah	RCREG		9Ah
1Bh	CCPR2L		9Bh
1Ch	CCPR2H		9Ch
1Dh	CCP2CON		9Dh
1Eh	ADRES		9Eh
1Fh	ADCON0	ADCON1	9Fh
20h			A0h
	General Purpose Register	General Purpose Register	
7Fh			FFh
	Bank 0	Bank 1	

 Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.  
 2: These registers are not physically implemented on the PIC16C73/73A, read as '0'.

## 7.2 Using Timer0 with an External Clock

Applicable Devices							
72	73	73A	74	74A	76	77	

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (Tosc). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

### 7.2.1 EXTERNAL CLOCK SYNCHRONIZATION

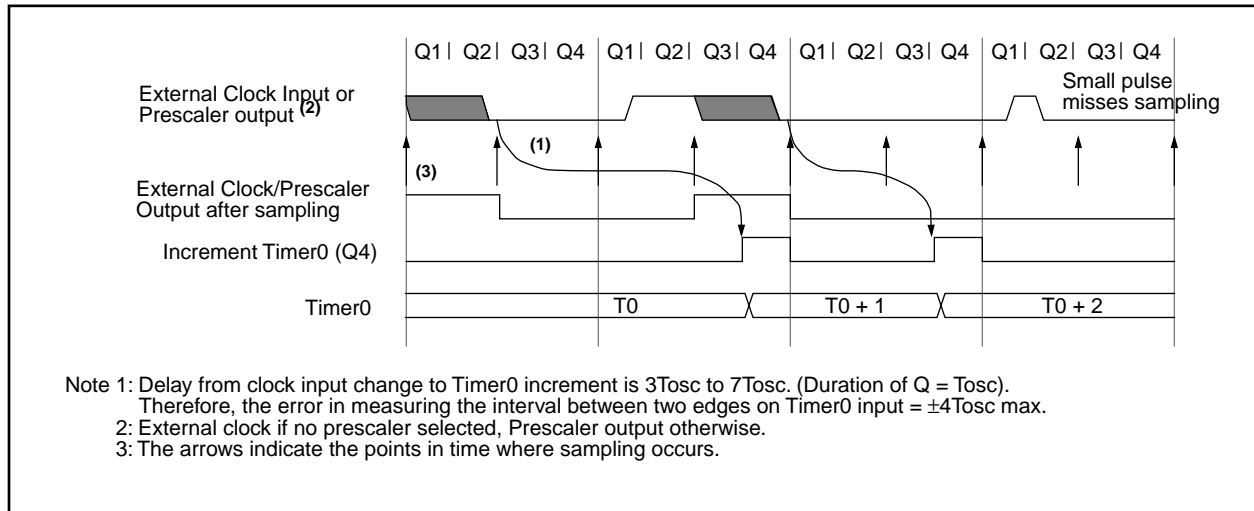
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 7-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

### 7.2.2 TMR0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 7-5 shows the delay from the external clock edge to the timer incrementing.

**FIGURE 7-5: TIMER0 TIMING WITH EXTERNAL CLOCK**



# PIC16C7X

**FIGURE 9-2: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)**

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	
bit7							bit0	

R = Readable bit  
W = Writable bit  
U = Unimplemented bit, read as '0'  
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6-3: **TOUTPS3:TOUTPS0:** Timer2 Output Postscale Select bits  
0000 = 1:1 Postscale  
0001 = 1:2 Postscale  
•  
•  
•  
1111 = 1:16 Postscale

bit 2: **TMR2ON:** Timer2 On bit  
1 = Timer2 is on  
0 = Timer2 is off

bit 1-0: **T2CKPS1:T2CKPS0:** Timer2 Clock Prescale Select bits  
00 = Prescaler is 1  
01 = Prescaler is 4  
1x = Prescaler is 16

**TABLE 9-1: REGISTERS ASSOCIATED WITH TIMER2 AS A TIMER/COUNTER**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF <sup>(1,2)</sup>	ADIF	RCIF <sup>(2)</sup>	TXIF <sup>(2)</sup>	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE <sup>(1,2)</sup>	ADIE	RCIE <sup>(2)</sup>	TXIE <sup>(2)</sup>	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
92h	PR2	Timer2 Period Register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the Timer2 module.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A/76, always maintain these bits clear.

Note 2: The PIC16C72 does not have a Parallel Slave Port or a USART, these bits are unimplemented, read as '0'.

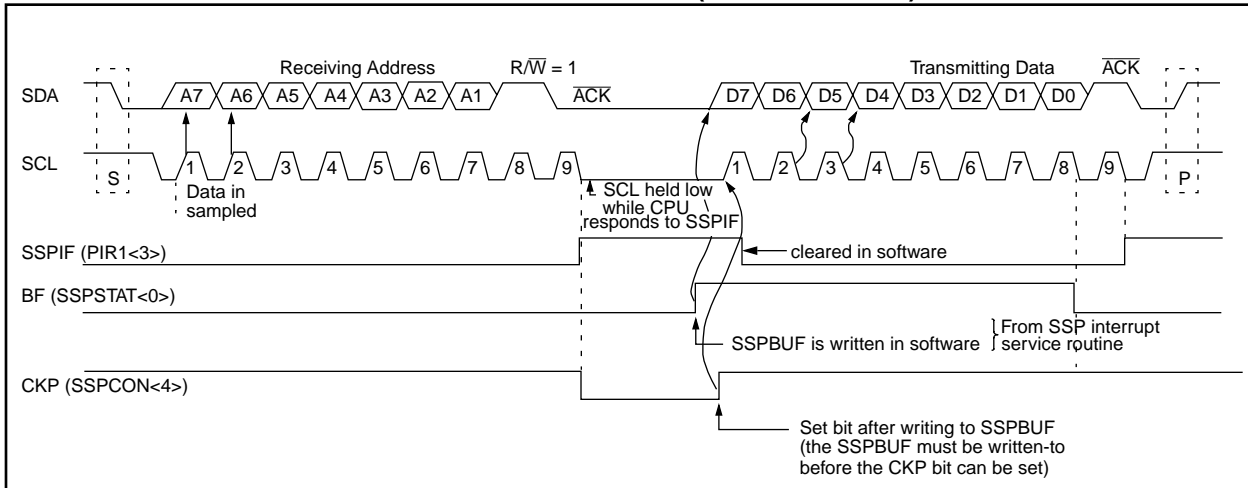
## 11.5.1.3 TRANSMISSION

When the  $R/\overline{W}$  bit of the incoming address byte is set and an address match occurs, the  $R/\overline{W}$  bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The  $\overline{ACK}$  pulse will be sent on the ninth bit, and pin RC3/SCK/SCL is held low. The transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP (SSPCON<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 11-26).

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software, and the SSPSTAT register is used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the  $\overline{ACK}$  pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not  $\overline{ACK}$ ), then the data transfer is complete. When the  $\overline{ACK}$  is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave then monitors for another occurrence of the START bit. If the SDA line was low ( $\overline{ACK}$ ), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP.

**FIGURE 11-26: I<sup>2</sup>C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)**



## 12.1 USART Baud Rate Generator (BRG)

Applicable Devices							
72	73	73A	74	74A	76	77	

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In asynchronous mode bit BRGH (TXSTA<2>) also controls the baud rate. In synchronous mode bit BRGH is ignored. Table 12-1 shows the formula for computation of the baud rate for different USART modes which only apply in master mode (internal clock).

Given the desired baud rate and Fosc, the nearest integer value for the SPBRG register can be calculated using the formula in Table 12-1. From this, the error in baud rate can be determined.

Example 12-1 shows the calculation of the baud rate error for the following conditions:

FOSC = 16 MHz  
Desired Baud Rate = 9600  
BRGH = 0  
SYNC = 0

### EXAMPLE 12-1: CALCULATING BAUD RATE ERROR

$$\begin{aligned}\text{Desired Baud rate} &= \text{Fosc} / (64 (X + 1)) \\ 9600 &= 16000000 / (64 (X + 1)) \\ X &= \lfloor 25.042 \rfloor = 25 \\ \text{Calculated Baud Rate} &= 16000000 / (64 (25 + 1)) \\ &= 9615 \\ \text{Error} &= \frac{(\text{Calculated Baud Rate} - \text{Desired Baud Rate})}{\text{Desired Baud Rate}} \\ &= (9615 - 9600) / 9600 \\ &= 0.16\%\end{aligned}$$

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the  $\text{Fosc}/(16(X + 1))$  equation can reduce the baud rate error in some cases.

**Note:** For the PIC16C73/73A/74/74A, the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information, or use the PIC16C76/77.

Writing a new value to the SPBRG register, causes the BRG timer to be reset (or cleared), this ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

**TABLE 12-1: BAUD RATE FORMULA**

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = $\text{Fosc}/(64(X+1))$	Baud Rate = $\text{Fosc}/(16(X+1))$
1	(Synchronous) Baud Rate = $\text{Fosc}/(4(X+1))$	NA

X = value in SPBRG (0 to 255)

**TABLE 12-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used by the BRG.

**TABLE 12-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE TRANSMISSION**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF <sup>(1)</sup>	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Transmit Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE <sup>(1)</sup>	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Synchronous Slave Transmission.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A/76, always maintain these bits clear.

**TABLE 12-11: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF <sup>(1)</sup>	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
1Ah	RCREG	USART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE <sup>(1)</sup>	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Synchronous Slave Reception.

Note 1: Bits PSPIE and PSPIF are reserved on the PIC16C73/73A/76, always maintain these bits clear.



## 14.4.5 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 14-10, Figure 14-11, and Figure 14-12 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if  $\overline{\text{MCLR}}$  is kept low long enough, the time-outs will expire. Then bringing MCLR high will begin execution immediately (Figure 14-11). This is useful for testing purposes or to synchronize more than one PIC16CXX device operating in parallel.

Table 14-7 shows the reset conditions for some special function registers, while Table 14-8 shows the reset conditions for all the registers.

## 14.4.6 POWER CONTROL/STATUS REGISTER (PCON)

Applicable Devices					
72	73	73A	74	74A	76/77

The Power Control/Status Register, PCON has up to two bits, depending upon the device. Bit0 is not implemented on the PIC16C73 or PIC16C74.

Bit0 is Brown-out Reset Status bit,  $\overline{\text{BOR}}$ . Bit  $\overline{\text{BOR}}$  is unknown on a Power-on Reset. It must then be set by the user and checked on subsequent resets to see if bit  $\overline{\text{BOR}}$  cleared, indicating a BOR occurred. The  $\overline{\text{BOR}}$  bit is a "Don't Care" bit and is not necessarily predictable if the Brown-out Reset circuitry is disabled (by clearing bit BODEN in the Configuration Word).

Bit1 is  $\overline{\text{POR}}$  (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

**TABLE 14-3: TIME-OUT IN VARIOUS SITUATIONS, PIC16C73/74**

Oscillator Configuration	Power-up		Wake-up from SLEEP
	PWRTE = 1	PWRTE = 0	
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	1024Tosc
RC	72 ms	—	—

**TABLE 14-4: TIME-OUT IN VARIOUS SITUATIONS, PIC16C72/73A/74A/76/77**

Oscillator Configuration	Power-up		Brown-out	Wake-up from SLEEP
	PWRTE = 0	PWRTE = 1		
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	72 ms + 1024Tosc	1024Tosc
RC	72 ms	—	72 ms	—

**TABLE 14-5: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C73/74**

POR	$\overline{\text{TO}}$	$\overline{\text{PD}}$	
0	1	1	Power-on Reset
0	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	1	WDT Reset
1	0	0	WDT Wake-up
1	u	u	MCLR Reset during normal operation
1	1	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP

Legend: u = unchanged, x = unknown

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**TABLE 14-6: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C72/73A/74A/76/77**

POR	BOR	TO	PD	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, $\overline{TO}$ is set on POR
0	x	x	0	Illegal, $\overline{PD}$ is set on POR
1	0	x	x	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR Reset during normal operation
1	1	1	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP

**TABLE 14-7: RESET CONDITION FOR SPECIAL REGISTERS**

Condition	Program Counter	STATUS Register	PCON Register PIC16C73/74	PCON Register PIC16C72/73A/74A/76/77
Power-on Reset	000h	0001 1xxx	---- --0-	---- --0x
MCLR Reset during normal operation	000h	000u uuuu	---- --u-	---- --uu
MCLR Reset during SLEEP	000h	0001 0uuu	---- --u-	---- --uu
WDT Reset	000h	0000 1uuu	---- --u-	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --u-	---- --uu
Brown-out Reset	000h	0001 1uuu	N/A	---- --u0
Interrupt wake-up from SLEEP	PC + 1 <sup>(1)</sup>	uuu1 0uuu	---- --u-	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

**TABLE 14-8: INITIALIZATION CONDITIONS FOR ALL REGISTERS**

Register	Applicable Devices							Power-on Reset, Brown-out Reset	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
W	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	72	73	73A	74	74A	76	77	N/A	N/A	N/A
TMR0	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	72	73	73A	74	74A	76	77	0000h	0000h	PC + 1 <sup>(2)</sup>
STATUS	72	73	73A	74	74A	76	77	0001 1xxx	000q quuu <sup>(3)</sup>	uuuq quuu <sup>(3)</sup>
FSR	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	72	73	73A	74	74A	76	77	--0x 0000	--0u 0000	--uu uuuu
PORTB	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTD	72	73	73A	74	74A	76	77	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTE	72	73	73A	74	74A	76	77	---- -xxx	---- -uuu	---- -uuu
PCLATH	72	73	73A	74	74A	76	77	---0 0000	---0 0000	---u uuuu

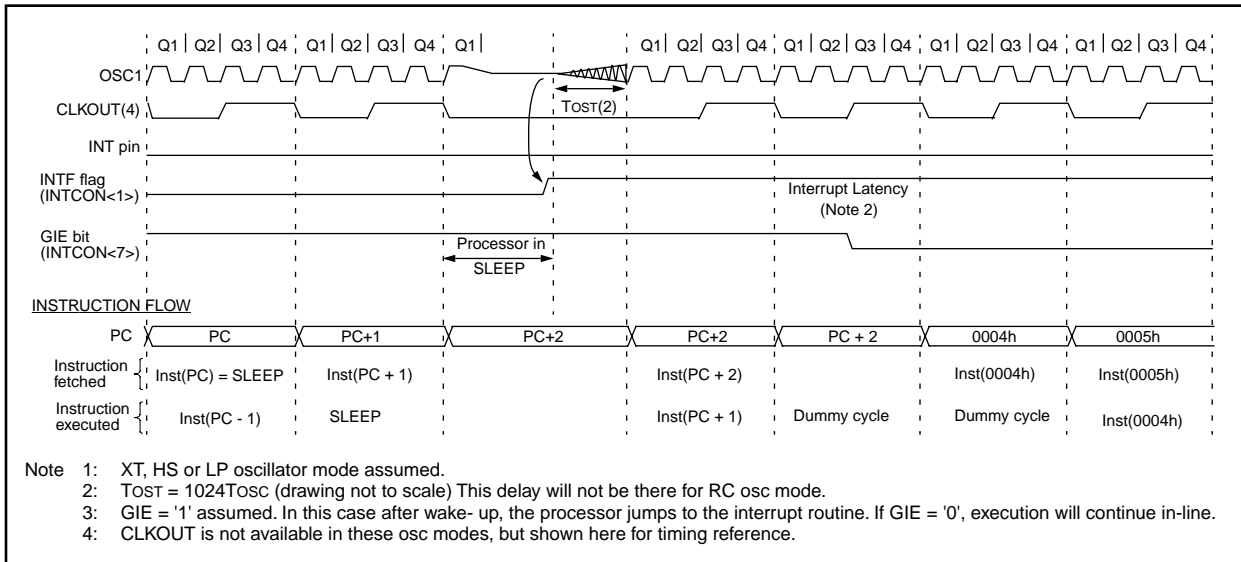
Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 14-7 for reset value for specific condition.

**FIGURE 14-20: WAKE-UP FROM SLEEP THROUGH INTERRUPT**



## 14.9 Program Verification/Code Protection

Applicable Devices
727373A7474A7677

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

**Note:** Microchip does not recommend code protecting windowed devices.

## 14.10 ID Locations

Applicable Devices
727373A7474A7677

Four memory locations (2000h - 2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify. It is recommended that only the 4 least significant bits of the ID location are used.

## 14.11 In-Circuit Serial Programming

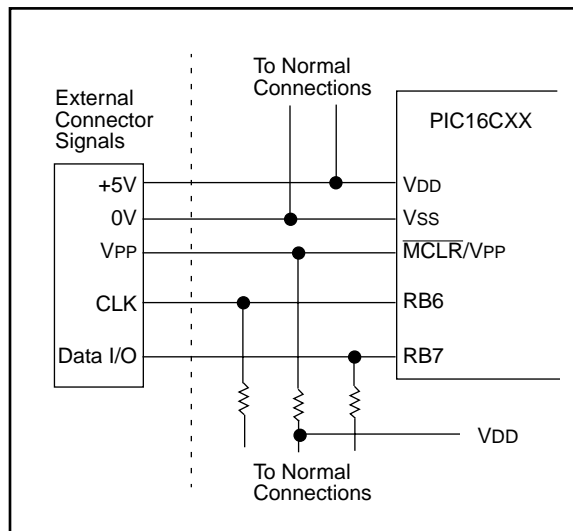
Applicable Devices
727373A7474A7677

PIC16CXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the RB6 and RB7 pins low while raising the MCLR (VPP) pin from VIL to VIH (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After reset, to place the device into programming/verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

**FIGURE 14-21: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION**



# PIC16C7X

Applicable Devices 72 73 73A 74 74A 76 77

## 17.1 DC Characteristics: PIC16C72-04 (Commercial, Industrial, Extended) PIC16C72-10 (Commercial, Industrial, Extended) PIC16C72-20 (Commercial, Industrial, Extended)

Standard Operating Conditions (unless otherwise stated)							
DC CHARACTERISTICS							
Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	- -	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset Signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset Signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7 3.7	4.0 4.0	4.3 4.4	V V	BODEN bit in configuration word enabled Extended Only
D010  D013	Supply Current (Note 2,5)	IDD	- -	2.7 10	5.0 20	mA mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)  HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled VDD = 5.0V
D020 D021 D021A D021B	Power-down Current (Note 3,5)	IPD	- - - -	10.5 1.5 1.5 2.5	42 16 19 19	μA μA μA μA	VDD = 4.0V, WDT enabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -0°C to +70°C VDD = 4.0V, WDT disabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled VDD = 5.0V

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula  $I_r = V_{DD}/2R_{ext}$  (mA) with Rext in kOhm.

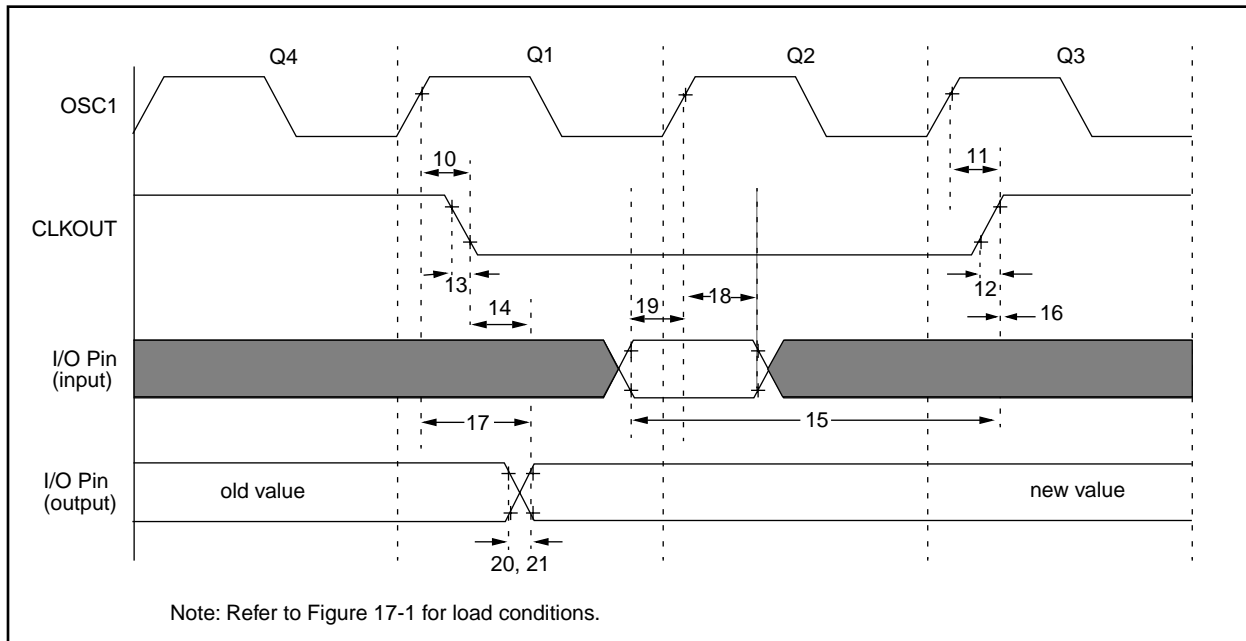
5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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**FIGURE 17-3: CLKOUT AND I/O TIMING**



**TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	—	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	75	200	ns	Note 1
12*	TckR	CLKOUT rise time	—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time	—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid	—	—	0.5T <sub>cy</sub> + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	Tosc + 200	—	—	ns	Note 1
16*	TckH2ioI	Port in hold after CLKOUT ↑	0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	50	150	ns	
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16C72	100	—	—	ns
			PIC16LC72	200	—	—	ns
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns	
20*	TioR	Port output rise time	PIC16C72	—	10	40	ns
			PIC16LC72	—	—	80	ns
21*	TioF	Port output fall time	PIC16C72	—	10	40	ns
			PIC16LC72	—	—	80	ns
22††*	Tinp	INT pin high or low time	T <sub>cy</sub>	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time	T <sub>cy</sub>	—	—	ns	

\* These parameters are characterized but not tested.

†Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x T<sub>osc</sub>.

**TABLE 17-10: A/D CONVERTER CHARACTERISTICS:**  
**PIC16C72-04 (Commercial, Industrial, Extended)**  
**PIC16C72-10 (Commercial, Industrial, Extended)**  
**PIC16C72-20 (Commercial, Industrial, Extended)**  
**PIC16LC72-04 (Commercial, Industrial)**

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	NR	Resolution		—	—	8-bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A02	EABS	Total Absolute error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A05	EFS	Full scale error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error		—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity		—	guaranteed	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage		3.0V	—	VDD + 0.3	V	
A25	VAIN	Analog input voltage		VSS - 0.3	—	VREF + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	PIC16C72	—	180	—	μA	Average current consumption when A/D is on. (Note 1)
			PIC16LC72	—	90	—	μA	
A50	IREF	VREF input current (Note 2)		10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 13.1.
				—	—	10	μA	During A/D Conversion cycle

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.

The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

## 18.0 ELECTRICAL CHARACTERISTICS FOR PIC16C73/74

### Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$ , and RA4)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 2)	0 to +14V
Voltage on RA4 with respect to VSS	0 to +14V
Total power dissipation (Note 1)	1.0W
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > VDD)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > VDD)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3)	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3)	200 mA
Maximum current sunk by PORTC and PORTD (combined) (Note 3)	200 mA
Maximum current sourced by PORTC and PORTD (combined) (Note 3)	200 mA

**Note 1:** Power dissipation is calculated as follows:  $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

**Note 2:** Voltage spikes below VSS at the  $\overline{\text{MCLR}}$  pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the  $\overline{\text{MCLR}}$  pin rather than pulling this pin directly to VSS.

**Note 3:** PORTD and PORTE are not implemented on the PIC16C73.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**TABLE 18-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)**

OSC	PIC16C73-04 PIC16C74-04	PIC16C73-10 PIC16C74-10	PIC16C73-20 PIC16C74-20	PIC16LC73-04 PIC16LC74-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 13.5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.7 mA typ. at 5.5V IPD: 1.5 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 13.5 µA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 21 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 15 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.5 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 52.5 µA typ. at 32 kHz, 4.0V IPD: 0.9 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 13.5 µA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 48 µA max. at 32 kHz, 3.0V IPD: 13.5 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

## 18.2 DC Characteristics: PIC16LC73/74-04 (Commercial, Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated)					
		Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001	Supply Voltage	VDD	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2,5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	Power-down Current (Note 3,5)	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	13.5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	18	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula  $I_r = V_{DD}/2R_{ext}$  (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.



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## 19.1 DC Characteristics: PIC16C73A/74A-04 (Commercial, Industrial, Extended) PIC16C73A/74A-10 (Commercial, Industrial, Extended) PIC16C73A/74A-20 (Commercial, Industrial, Extended)

Standard Operating Conditions (unless otherwise stated)							
DC CHARACTERISTICS							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	- -	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7 3.7	4.0 4.0	4.3 4.4	V V	BODEN bit in configuration word enabled Extended Range Only
D010  D013  D015*	Supply Current (Note 2,5)   Brown-out Reset Current (Note 6)	IDD   $\Delta$ IBOR	-  - -	2.7 10 350	5 20 425	mA mA $\mu$ A	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)  HS osc configuration FOSC = 20 MHz, VDD = 5.5V  BOR enabled VDD = 5.0V
D020 D021 D021A D021B D023*	Power-down Current (Note 3,5)    Brown-out Reset Current (Note 6)	IPD    $\Delta$ IBOR	- - - - -	10.5 1.5 1.5 2.5 350	42 16 19 19 425	$\mu$ A $\mu$ A $\mu$ A $\mu$ A $\mu$ A	VDD = 4.0V, WDT enabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -0°C to +70°C VDD = 4.0V, WDT disabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -40°C to +125°C BOR enabled VDD = 5.0V

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula  $I_r = VDD/2R_{ext}$  (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20  $\mu$ A to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The  $\Delta$  current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

**20.1 DC Characteristics:**    **PIC16C76/77-04 (Commercial, Industrial, Extended)**  
**PIC16C76/77-10 (Commercial, Industrial, Extended)**  
**PIC16C76/77-20 (Commercial, Industrial, Extended)**

<b>DC CHARACTERISTICS</b> <div> <b>Standard Operating Conditions (unless otherwise stated)</b>  Operating temperature    -40°C    ≤ TA ≤ +125°C for extended,  -40°C    ≤ TA ≤ +85°C for industrial and  0°C    ≤ TA ≤ +70°C for commercial </div>							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001 D001A	Supply Voltage	VDD	4.0 4.5	- -	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7 3.7	4.0 4.0	4.3 4.4	V V	BODEN bit in configuration word enabled Extended Range Only
D010  D013	Supply Current (Note 2,5)	IDD	- -	2.7 10	5 20	mA mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)  HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled VDD = 5.0V
D020 D021 D021A D021B	Power-down Current (Note 3,5)	IPD	- - - -	10.5 1.5 1.5 2.5	42 16 19 19	μA μA μA μA	VDD = 4.0V, WDT enabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -0°C to +70°C VDD = 4.0V, WDT disabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -40°C to +125°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled VDD = 5.0V

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula  $I_r = VDD/2R_{ext}$  (mA) with Rext in kOhm.

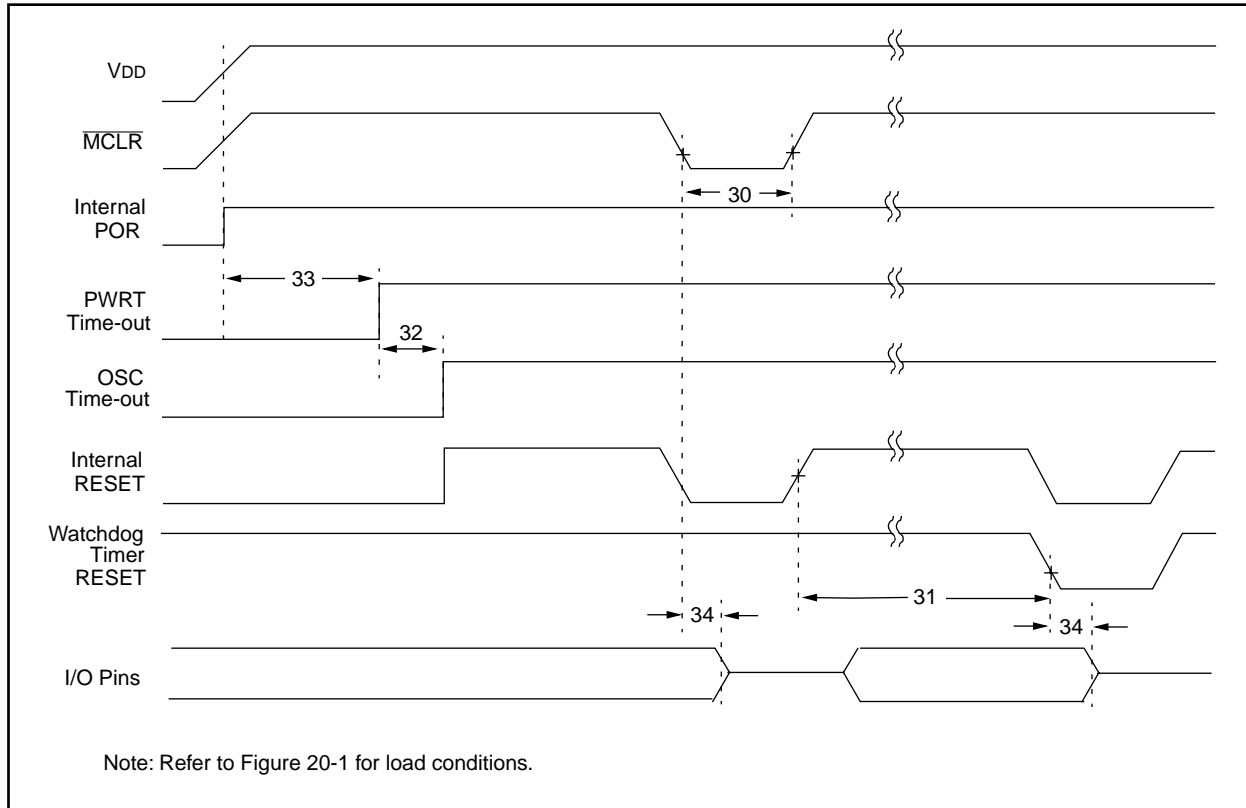
5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

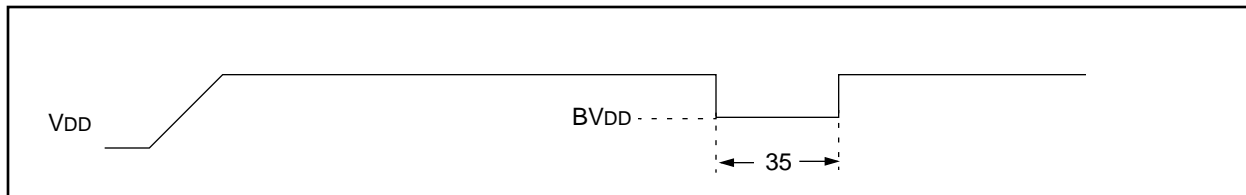
# PIC16C7X

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**FIGURE 20-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING**



**FIGURE 20-5: BROWN-OUT RESET TIMING**



**TABLE 20-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	2	—	—	μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc	—	—	Tosc = OSC1 period
33*	Tpwrt	Power up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or Watchdog Timer Reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset pulse width	100	—	—	μs	VDD ≤ BVDD (D005)

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 21-16: TYPICAL I<sub>DD</sub> vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

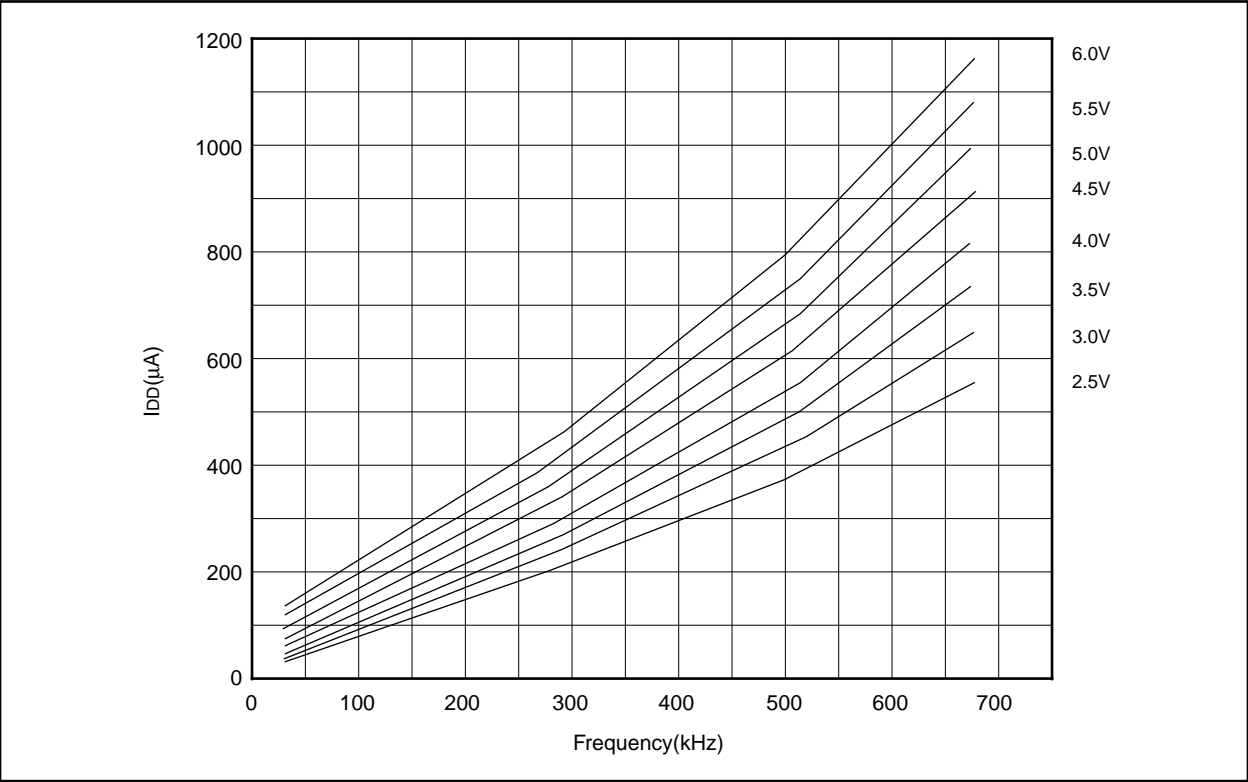
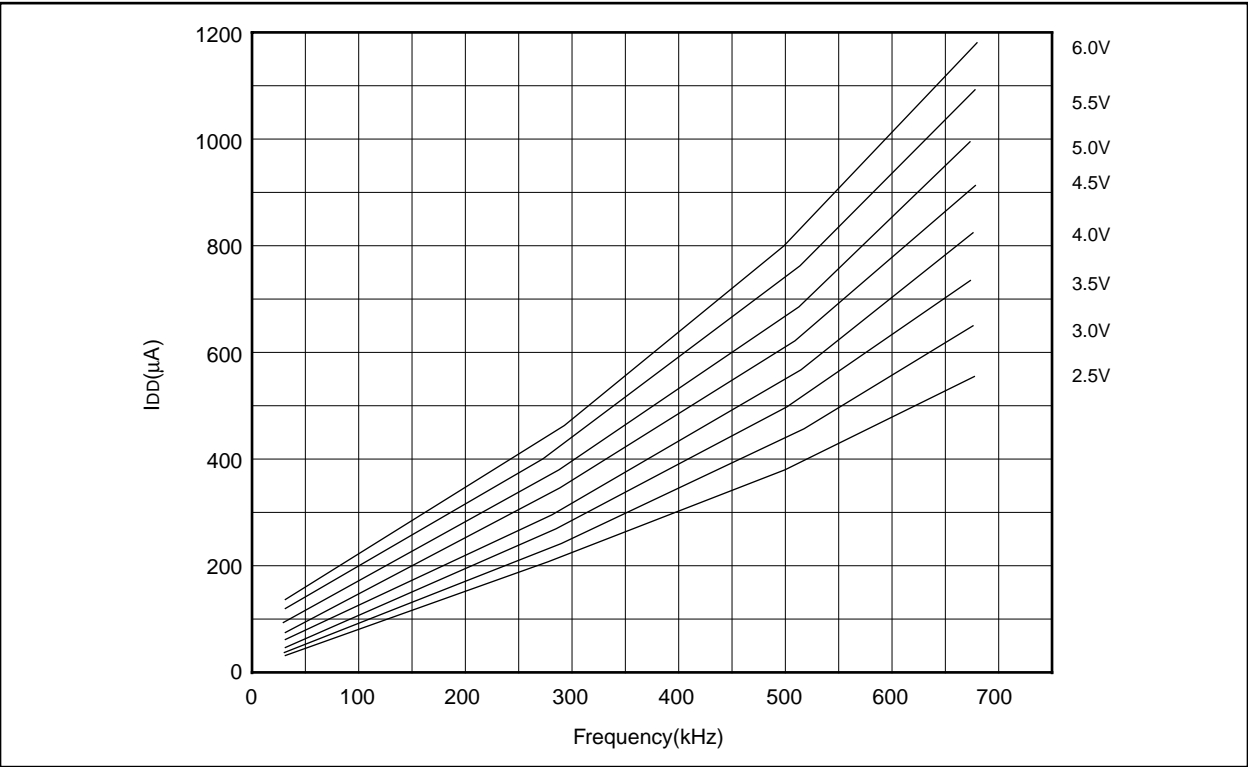


FIGURE 21-17: MAXIMUM I<sub>DD</sub> vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Data based on matrix samples. See first page of this section for details.

## APPENDIX A:

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake up from SLEEP through interrupt is added.
11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. T0CKI pin is also a port pin (RA4) now.
14. FSR is made a full eight bit register.
15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS,  $\overline{\text{MCLR}}$ /VPP, RB6 (clock) and RB7 (data in/out).
16. PCON status register is added with a Power-on Reset status bit (POR).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. Brown-out protection circuitry has been added. Controlled by configuration word bit BODEN. Brown-out reset ensures the device is placed in a reset condition if VDD dips below a fixed set-point.

## APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change reset vector to 0000h.